

# DA5J110V

## Silicon epitaxial planar type

For high speed switching circuits

### ■ Features

- Short reverse recovery time  $t_{rr}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	80	V
Maximum peak reverse voltage	$V_{RM}$	80	V
Forward current	$I_F$	100	mA
Peak forward current *1	$I_{FM}$	225	mA
Non-repetitive peak forward surge current *2	$I_{FSM}$	500	mA
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*1: Value for single diode

\*2: 1 t = 1 s

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

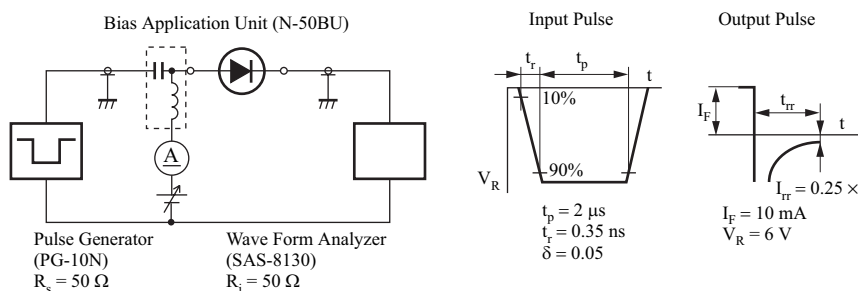
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 100 \text{ mA}$			1.2	V
Reverse voltage	$V_R$	$I_R = 100 \mu\text{A}$	80			V
Reverse current	$I_R$	$V_R = 80 \text{ V}$			100	nA
Terminal capacitance	$C_t$	$V_R = 6 \text{ V}, f = 1 \text{ MHz}$			3.5	pF
Reverse recovery time *1	$t_{rr}$	$I_F = 5 \text{ mA}, V_R = 6 \text{ V}, I_{rr} = 0.25 \times I_R$			5.0	ns
Transistor current *2	$I_C$	$V = \pm 8 \text{ V}, I = 1 \text{ mA}$		30		$\mu\text{A}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz

3. \*1:  $t_{rr}$  measurement circuit

\*2: Lead 2 is applied current and Lead1-3 or Lead3-4 or Lead4-5 or Lead5-1 is applied voltage.



### ■ Package

#### • Code

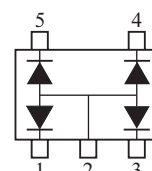
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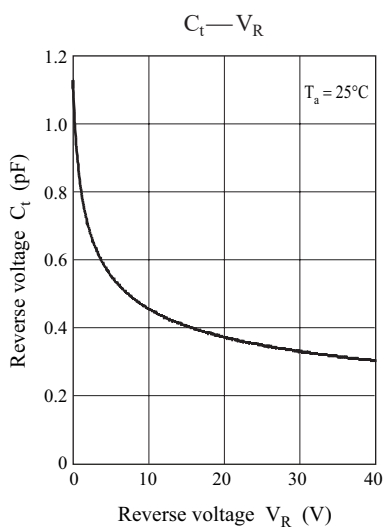
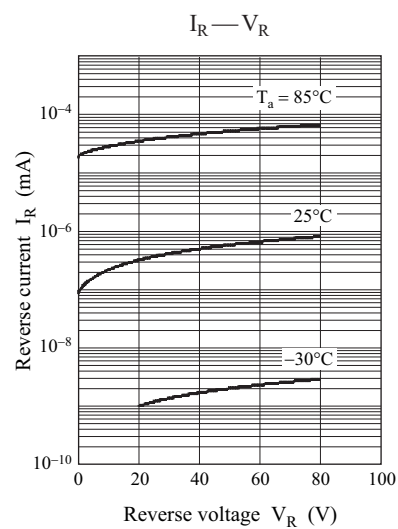
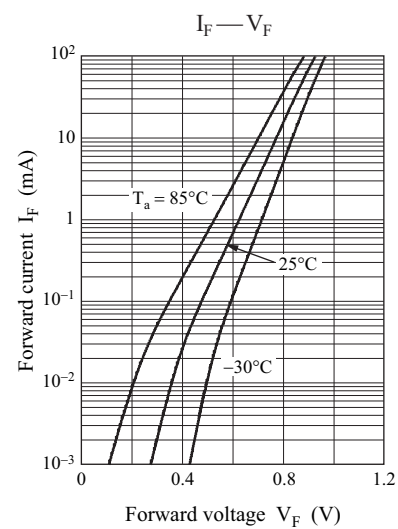
#### • Pin Name

- 1: Cathode-1      4: Cathode-3
- 2: Anode-1, 2, 3, 4      5: Cathode-4
- 3: Cathode-2

### ■ Marking Symbol: 27

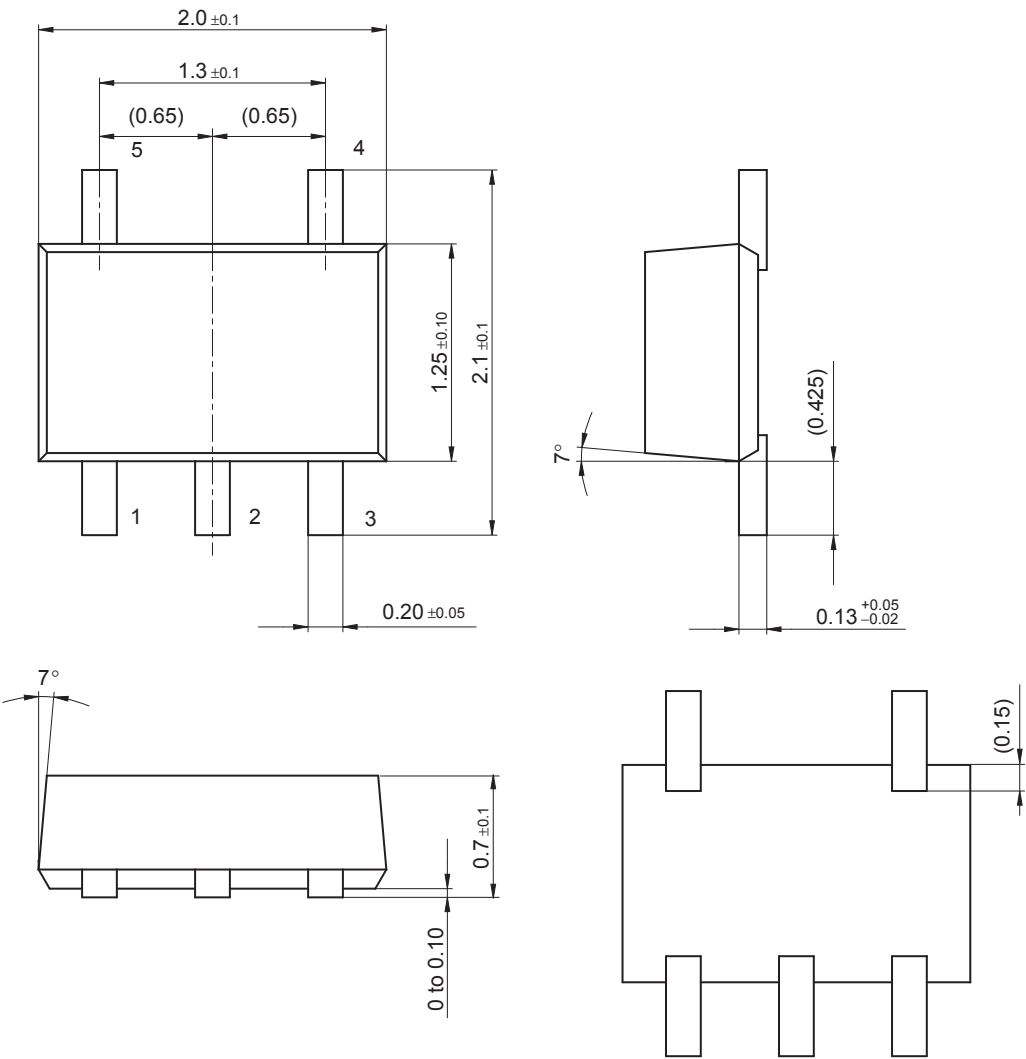
### ■ Internal Connection





SMini5-F3-B

Unit: mm



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